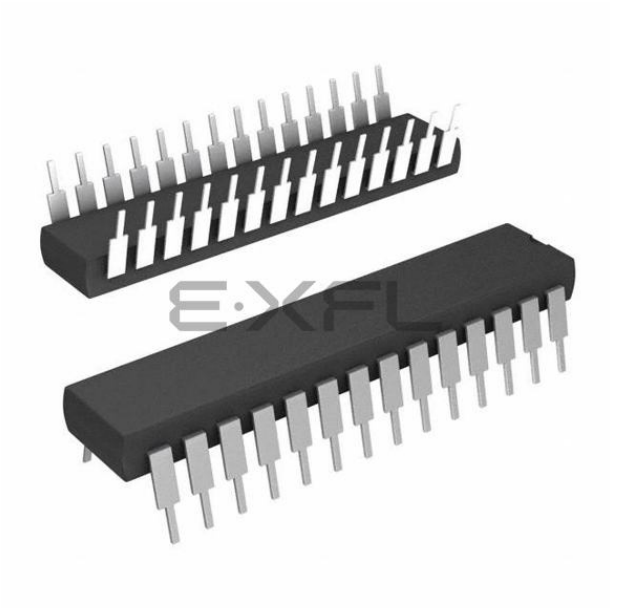
Microchip Technology - PIC24EP256GP202-I/SP Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

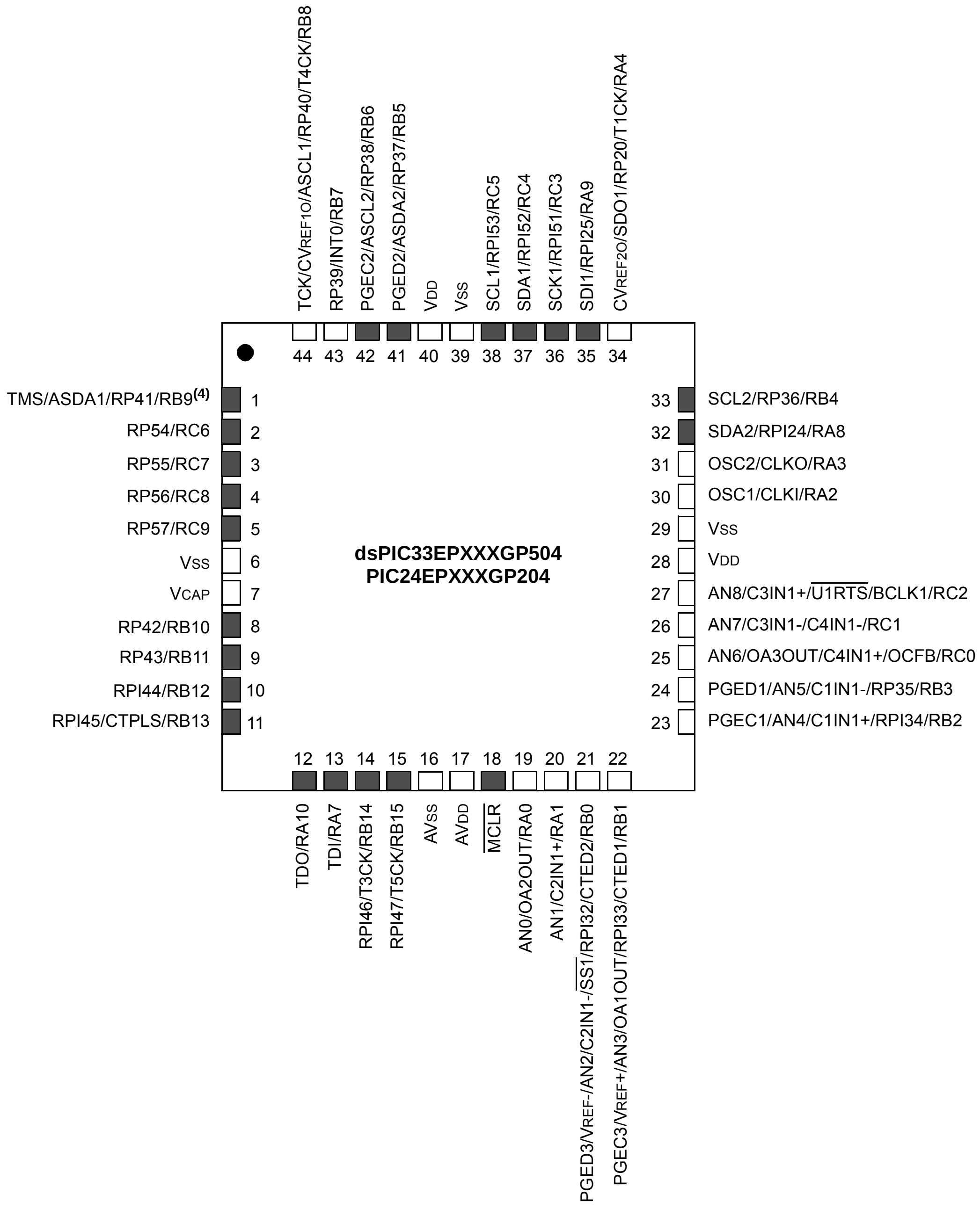
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256gp202-i-sp

Pin Diagrams (Continued)

44-Pin QFN[1,2,3]

■ = Pins are up to 5V tolerant



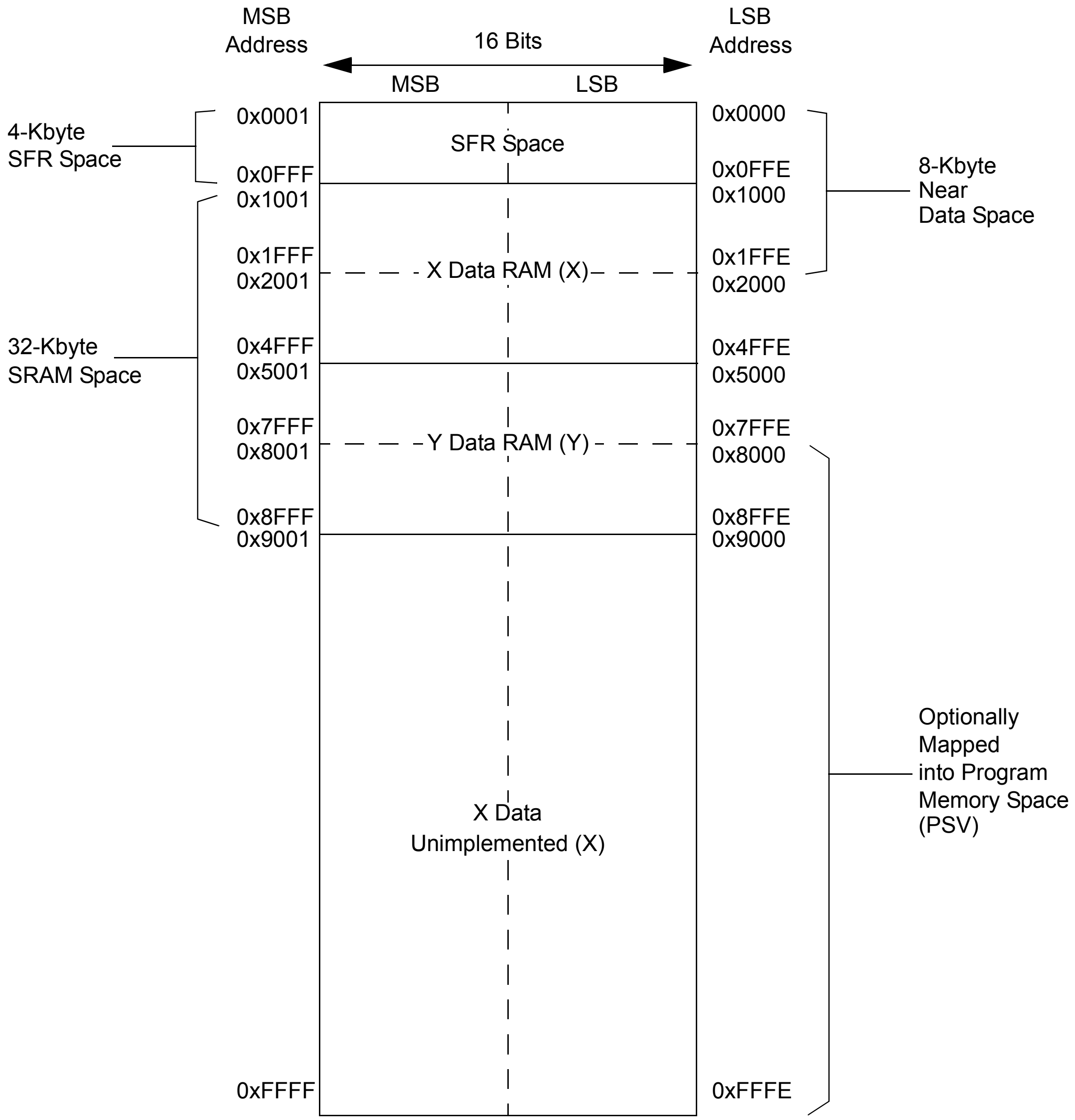
Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-10: DATA MEMORY MAP FOR dsPIC33EP256MC20X/50X AND dsPIC33EP256GP50X DEVICES



Note: Memory areas are not shown to scale.

4.4.3 DATA MEMORY ARBITRATION AND BUS MASTER PRIORITY

EDS accesses from bus masters in the system are arbitrated.

The arbiter for data memory (including EDS) arbitrates between the CPU, the DMA and the ICD module. In the event of coincidental access to a bus by the bus masters, the arbiter determines which bus master access has the highest priority. The other bus masters are suspended and processed after the access of the bus by the bus master with the highest priority.

By default, the CPU is Bus Master 0 (M0) with the highest priority and the ICD is Bus Master 4 (M4) with the lowest priority. The remaining bus master (DMA Controller) is allocated to M3 (M1 and M2 are reserved and cannot be used). The user application may raise or lower the priority of the DMA Controller to be above that of the CPU by setting the appropriate bits in the EDS Bus Master Priority Control (MSTRPR) register. All bus masters with raised priorities will maintain the same priority relationship relative to each other (i.e., M1 being highest and M3 being lowest, with M2 in between). Also, all the bus masters with priorities below that of the CPU maintain the same priority relationship relative to each other. The priority schemes for bus masters with different MSTRPR values are tabulated in Table 4-62.

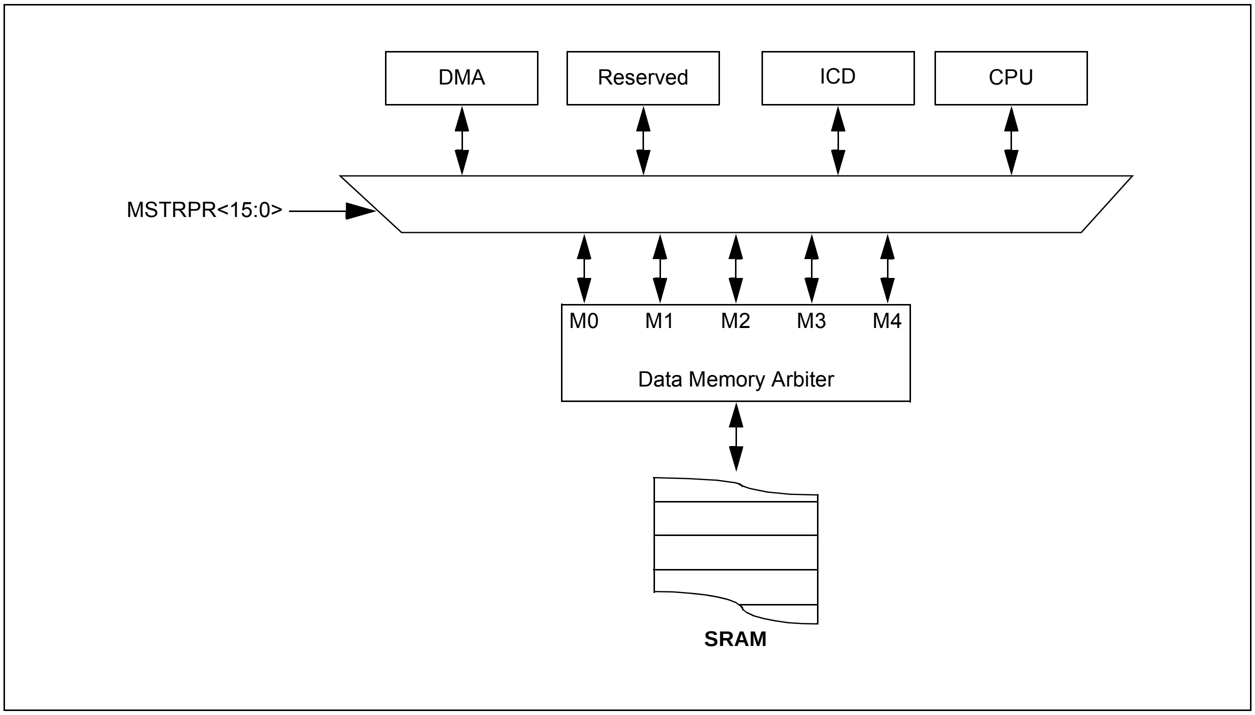
This bus master priority control allows the user application to manipulate the real-time response of the system, either statically during initialization or dynamically in response to real-time events.

TABLE 4-62: DATA MEMORY BUS ARBITER PRIORITY

Priority	MSTRPR<15:0> Bit Setting[1]	
	0x0000	0x0020
M0 (highest)	CPU	DMA
M1	Reserved	CPU
M2	Reserved	Reserved
M3	DMA	Reserved
M4 (lowest)	ICD	ICD

Note 1: All other values of MSTRPR<15:0> are reserved.

FIGURE 4-18: ARBITER ARCHITECTURE



10.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the `PWRSAV` instruction is shown in Example 10-1.

Note: `SLEEP_MODE` and `IDLE_MODE` are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 10-1: `PWRSAV` INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

10.2.1 SLEEP MODE

The following occurs in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals can continue to operate. This includes items such as the Input Change Notification (ICN) on the I/O ports or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled.

The device wakes up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

For optimal power savings, the internal regulator and the Flash regulator can be configured to go into Standby when Sleep mode is entered by clearing the VREGS (RCON<8>) and VREGSF (RCON<11>) bits (default configuration).

If the application requires a faster wake-up time, and can accept higher current requirements, the VREGS (RCON<8>) and VREGSF (RCON<11>) bits can be set to keep the internal regulator and the Flash regulator active during Sleep mode.

10.2.2 IDLE MODE

The following occurs in Idle mode:

- The CPU stops executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 “Peripheral Module Disable”**).
- If the WDT or FSCM is enabled, the LPRC also remains active.

The device wakes from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the `PWRSAV` instruction or the first instruction in the Interrupt Service Routine (ISR).

All peripherals also have the option to discontinue operation when Idle mode is entered to allow for increased power savings. This option is selectable in the control register of each peripheral; for example, the TSIDL bit in the Timer1 Control register (T1CON<13>).

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a `PWRSAV` instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

15.0 OUTPUT COMPARE

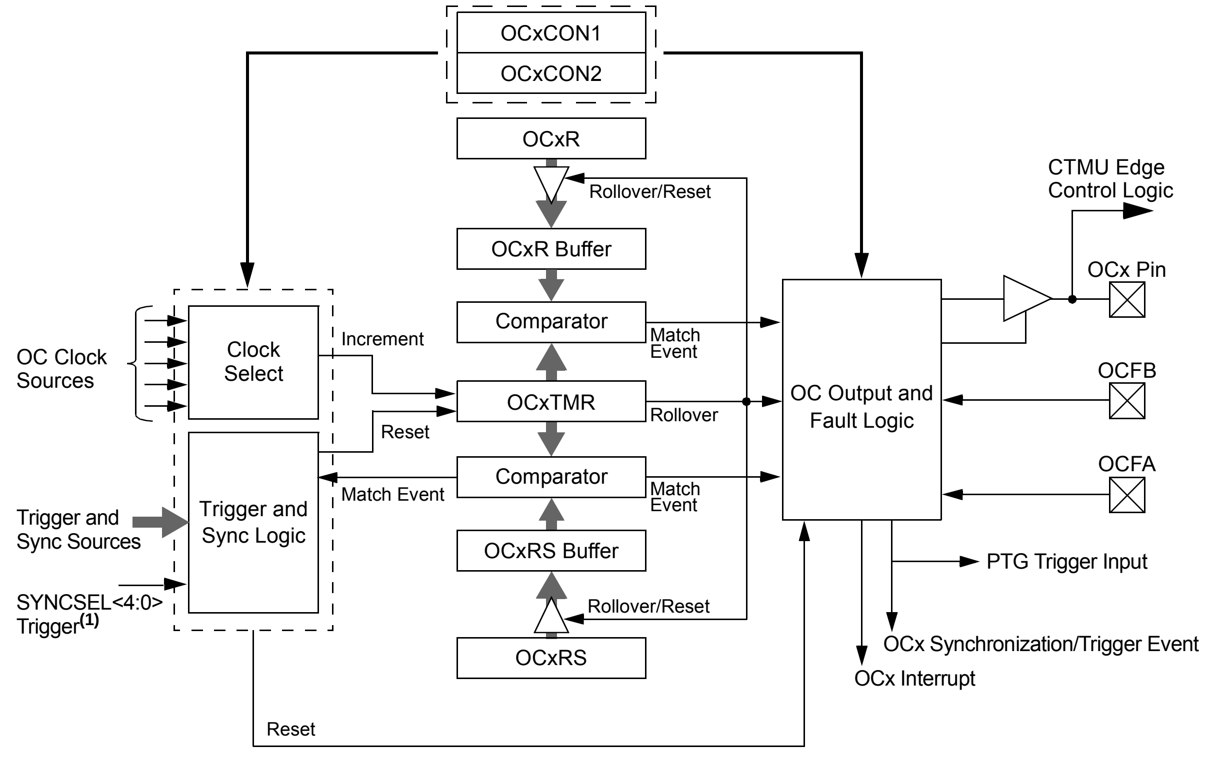
Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Output Compare"** (DS70358) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The output compare module can select one of seven available clock sources for its time base. The module compares the value of the timer with the value of one or two compare registers depending on the operating mode selected. The state of the output pin changes when the timer value matches the compare register value. The output compare module generates either a single output pulse or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events and trigger DMA data transfers.

Note: See **"Output Compare"** (DS70358) in the *"dsPIC33/PIC24 Family Reference Manual"* for OCxR and OCxRS register restrictions.

FIGURE 15-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



Note 1: The Trigger/Sync source is enabled by default and is set to Timer2 as a source. This timer must be enabled for proper OCx module operation or the Trigger/Sync source must be changed to another source option.

REGISTER 16-2: PTCON2: PWMx PRIMARY MASTER CLOCK DIVIDER SELECT REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PCLKDIV2(1)	PCLKDIV1(1)	PCLKDIV0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘`0`’

bit 2-0 **PCLKDIV<2:0>:** PWMx Input Clock Prescaler (Divider) Select bits(1)

`111` = Reserved
`110` = Divide-by-64
`101` = Divide-by-32
`100` = Divide-by-16
`011` = Divide-by-8
`010` = Divide-by-4
`001` = Divide-by-2
`000` = Divide-by-1, maximum PWMx timing resolution (power-on default)

Note 1: These bits should be changed only when PTEN = `0`. Changing the clock selection during operation will yield unpredictable results.

NOTES:

19.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **“Inter-Integrated Circuit™ (I^2C™)”** (DS70330) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

3: There are minimum bit rates of approximately FCY/512. As a result, high processor speeds may not support 100 Kbit/second operation. See timing specifications, IM10 and IM11, and the **“Baud Rate Generator”** in the “*dsPIC33/PIC24 Family Reference Manual*”.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices contains two Inter-Integrated Circuit (I^2C) modules: I2C1 and I2C2.

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The I^2C module has a 2-pin interface:

- The SCLx pin is clock
- The SDAx pin is data

The I^2C module offers the following key features:

- I^2C interface supporting both Master and Slave modes of operation
- I^2C Slave mode supports 7 and 10-bit addressing
- I^2C Master mode supports 7 and 10-bit addressing
- I^2C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation, detects bus collision and arbitrates accordingly
- Intelligent Platform Management Interface (IPMI) support
- System Management Bus (SMBus) support

REGISTER 19-2: I2CxSTAT: I2Cx STATUS REGISTER

R-0, HSC	R-0, HSC	U-0	U-0	U-0	R/C-0, HS	R-0, HSC	R-0, HSC
ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10
bit 15							bit 8

R/C-0, HS	R/C-0, HS	R-0, HSC	R/C-0, HSC	R/C-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HSC = Hardware Settable/Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**ACKSTAT:** Acknowledge Status bit (when operating as I^2C™ master, applicable to master transmit operation) 1 = NACK received from slave 0 = ACK received from slave Hardware is set or clear at the end of slave Acknowledge.
bit 14	**TRSTAT:** Transmit Status bit (when operating as I^2C master, applicable to master transmit operation) 1 = Master transmit is in progress (8 bits + ACK) 0 = Master transmit is not in progress Hardware is set at the beginning of master transmission. Hardware is clear at the end of slave Acknowledge.
bit 13-11	**Unimplemented:** Read as ‘0’
bit 10	**BCL:** Master Bus Collision Detect bit 1 = A bus collision has been detected during a master operation 0 = No bus collision detected Hardware is set at detection of a bus collision.
bit 9	**GCSTAT:** General Call Status bit 1 = General call address was received 0 = General call address was not received Hardware is set when address matches general call address. Hardware is clear at Stop detection.
bit 8	**ADD10:** 10-Bit Address Status bit 1 = 10-bit address was matched 0 = 10-bit address was not matched Hardware is set at the match of the 2nd byte of the matched 10-bit address. Hardware is clear at Stop detection.
bit 7	**IWCOL:** I2Cx Write Collision Detect bit 1 = An attempt to write to the I2CxTRN register failed because the I^2C module is busy 0 = No collision Hardware is set at the occurrence of a write to I2CxTRN while busy (cleared by software).
bit 6	**I2COV:** I2Cx Receive Overflow Flag bit 1 = A byte was received while the I2CxRCV register was still holding the previous byte 0 = No overflow Hardware is set at an attempt to transfer I2CxRSR to I2CxRCV (cleared by software).
bit 5	**D_A:** Data/Address bit (when operating as I^2C slave) 1 = Indicates that the last byte received was data 0 = Indicates that the last byte received was a device address Hardware is clear at a device address match. Hardware is set by reception of a slave byte.
bit 4	**P:** Stop bit 1 = Indicates that a Stop bit has been detected last 0 = Stop bit was not detected last Hardware is set or clear when a Start, Repeated Start or Stop is detected.

REGISTER 21-7: CxINTE: ECANx INTERRUPT ENABLE REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7 **IVRIE:** Invalid Message Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 6 **WAKIE:** Bus Wake-up Activity Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 5 **ERRIE:** Error Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 4 **Unimplemented:** Read as ‘0’

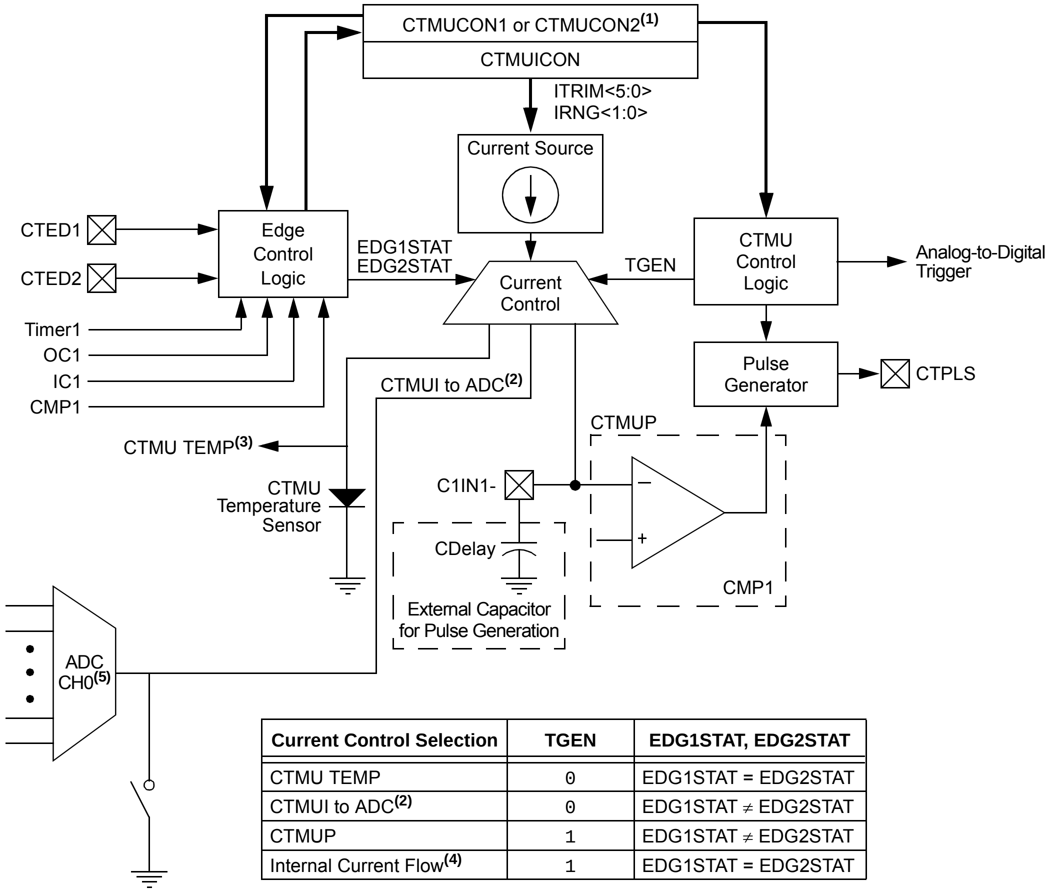
bit 3 **FIFOIE:** FIFO Almost Full Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 2 **RBOVIE:** RX Buffer Overflow Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **RBIE:** RX Buffer Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **TBIE:** TX Buffer Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

FIGURE 22-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMU TEMP	`0`	EDG1STAT = EDG2STAT
CTMUI to ADC(2)	`0`	EDG1STAT ≠ EDG2STAT
CTMUP	`1`	EDG1STAT ≠ EDG2STAT
Internal Current Flow(4)	`1`	EDG1STAT = EDG2STAT

Note 1: When the CTMU is not actively used, set TGEN = `1`, and ensure that EDG1STAT = EDG2STAT. All other settings allow current to flow into the ADC or the C1IN1- pin. If using the ADC for other purposes besides the CTMU, set IDISSEN = `0`. If IDISSEN is set to ‘`1`’, it will short the output of the ADC CH0 MUX to VSS.

2: CTMUI connects to the output of the ADC CH0 MUX. When CTMU current is steered into this node, the current will flow out through the selected ADC channel determined by the CH0 MUX (see the CH0Sx bits in the AD1CHS0 register).

3: CTMU TEMP connects to one of the ADC CH0 inputs; see CH0SA and CH0SB (AD1CHS0<12:8,4:0).

4: If TGEN = `1` and EDG1STAT = EDG2STAT, CTMU current source is still enabled and may be shunted to VSS internally. This should be considered in low-power applications.

5: The switch connected to ADC CH0 is closed when IDISSEN (CTMUCON1<9>) = `1`, and opened when IDISSEN = `0`.

22.1 CTMU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

22.1.1 KEY RESOURCES

- **“Charge Time Measurement Unit (CTMU)”** (DS70661) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

24.4 Step Commands and Format

TABLE 24-1: PTG STEP COMMAND FORMAT

Step Command Byte:	
STEPx<7:0>	
CMD<3:0>	OPTION<3:0>
bit 7 bit 4	bit 3 bit 0

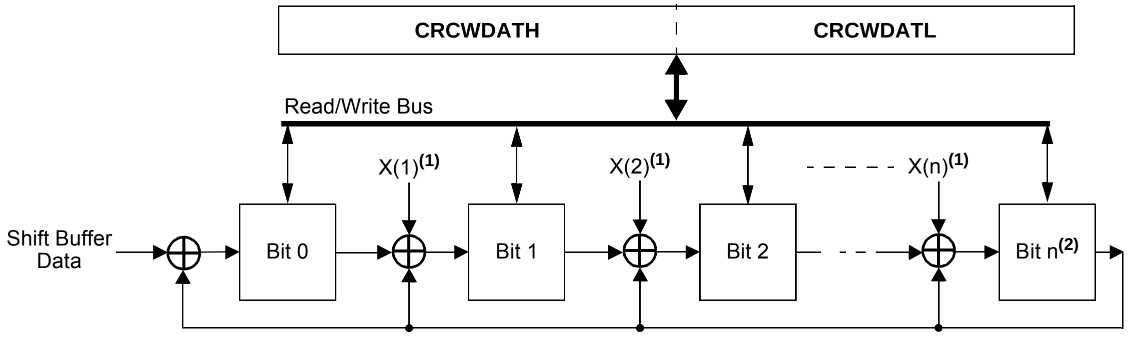
bit 7-4	**CMD<3:0>**	**Step Command**	**Command Description**
	0000	PTGCTRL	Execute control command as described by OPTION<3:0>.
	0001	PTGADD	Add contents of PTGADJ register to target register as described by OPTION<3:0>.
		PTGCOPY	Copy contents of PTGHOLD register to target register as described by OPTION<3:0>.
	001x	PTGSTRB	Copy the value contained in CMD<0>:OPTION<3:0> to the CH0SA<4:0> bits (AD1CHS0<4:0>).
	0100	PTGWHI	Wait for a low-to-high edge input from the selected PTG trigger input as described by OPTION<3:0>.
	0101	PTGWLO	Wait for a high-to-low edge input from the selected PTG trigger input as described by OPTION<3:0>.
	0110	Reserved	Reserved.
	0111	PTGIRQ	Generate individual interrupt request as described by OPTION3<:0>.
	100x	PTGTRIG	Generate individual trigger output as described by <<CMD<0>:OPTION<3:0>>.
	101x	PTGJMP	Copy the value indicated in <<CMD<0>:OPTION<3:0>> to the Queue Pointer (PTGQPTR) and jump to that Step queue.
	110x	PTGJMPC0	PTGC0 = PTGC0LIM: Increment the Queue Pointer (PTGQPTR).
			PTGC0 ≠ PTGC0LIM: Increment Counter 0 (PTGC0) and copy the value indicated in <<CMD<0>:OPTION<3:0>> to the Queue Pointer (PTGQPTR), and jump to that Step queue
	111x	PTGJMPC1	PTGC1 = PTGC1LIM: Increment the Queue Pointer (PTGQPTR).
			PTGC1 ≠ PTGC1LIM: Increment Counter 1 (PTGC1) and copy the value indicated in <<CMD<0>:OPTION<3:0>> to the Queue Pointer (PTGQPTR), and jump to that Step queue.

Note 1: All reserved commands or options will execute but have no effect (i.e., execute as a `NOP` instruction).

2: Refer to Table 24-2 for the trigger output descriptions.

3: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

FIGURE 26-2: CRC SHIFT ENGINE DETAIL



Note 1: Each XOR stage of the shift engine is programmable. See text for details.
2: Polynomial length n is determined by ([PLEN<4:0>] + 1).

26.1 Overview

The CRC module can be programmed for CRC polynomials of up to the 32nd order, using up to 32 bits. Polynomial length, which reflects the highest exponent in the equation, is selected by the PLEN<4:0> bits (CRCCON2<4:0>).

The CRCXORL and CRCXORH registers control which exponent terms are included in the equation. Setting a particular bit includes that exponent term in the equation; functionally, this includes an XOR operation on the corresponding bit in the CRC engine. Clearing the bit disables the XOR.

For example, consider two CRC polynomials, one a 16-bit equation and the other a 32-bit equation:

x16 + x12 + x5 + 1

and

x32 + x26 + x23 + x22 + x16 + x12 + x11 + x10 + x8 + x7 + x5 + x4 + x2 + x + 1

To program these polynomials into the CRC generator, set the register bits as shown in Table 26-1.

Note that the appropriate positions are set to ‘1’ to indicate that they are used in the equation (for example, X26 and X23). The 0 bit required by the equation is always XORed; thus, X0 is a don’t care. For a polynomial of length N, it is assumed that the *N*th bit will always be used, regardless of the bit setting. Therefore, for a polynomial length of 32, there is no 32nd bit in the CRCxOR register.

TABLE 26-1: CRC SETUP EXAMPLES FOR 16 AND 32-BIT POLYNOMIAL

CRC Control Bits	Bit Values	
	16-bit Polynomial	32-bit Polynomial
PLEN<4:0>	`01111`	`11111`
X<31:16>	`0000 0000` `0000 000x`	`0000 0100` `1100 0001`
X<15:0>	`0001 0000` `0010 000x`	`0001 1101` `1011 011x`

26.2 Programmable CRC Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

> **Note:** In the event you are not able to access the product page using the link above, enter this URL in your browser:
> http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

26.2.1 KEY RESOURCES

- **“Programmable Cyclic Redundancy Check (CRC)”** (DS70346) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
25	DAW	DAW Wn	Wn = decimal adjust Wn	1	1	C
26	DEC	DEC f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2 f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2 f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2 Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
28	DISI	DISI #lit14	Disable Interrupts for k instruction cycles	1	1	None
29	DIV	DIV.S Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF Wm,Wn(1)	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO #lit15,Expr(1)	Do code to PC + Expr, lit15 + 1 times	2	2	None
		DO Wn,Expr(1)	Do code to PC + Expr, (Wn) + 1 times	2	2	None
32	ED	ED Wm*Wm,Acc,Wx,Wy,Wxd(1)	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
33	EDAC	EDAC Wm*Wm,Acc,Wx,Wy,Wxd(1)	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
34	EXCH	EXCH Wns,Wnd	Swap Wns with Wnd	1	1	None
35	FBCL	FBCL Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	C
36	FF1L	FF1L Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
37	FF1R	FF1R Ws,Wnd	Find First One from Right (LSb) Side	1	1	C
38	GOTO	GOTO Expr	Go to address	2	4	None
		GOTO Wn	Go to indirect	1	4	None
		GOTO.L Wn	Go to indirect (long address)	1	4	None
39	INC	INC f	f = f + 1	1	1	C,DC,N,OV,Z
		INC f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
40	INC2	INC2 f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2 f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2 Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
41	IOR	IOR f	f = f .IOR. WREG	1	1	N,Z
		IOR f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR #lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
42	LAC	LAC Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
43	LNK	LNK #lit14	Link Frame Pointer	1	1	SFA
44	LSR	LSR f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
45	MAC	MAC Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB(1)	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd(1)	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
72	`SL`	`SL f`	f = Left Shift f	1	1	C,N,OV,Z
		`SL f,WREG`	WREG = Left Shift f	1	1	C,N,OV,Z
		`SL Ws,Wd`	Wd = Left Shift Ws	1	1	C,N,OV,Z
		`SL Wb,Wns,Wnd`	Wnd = Left Shift Wb by Wns	1	1	N,Z
		`SL Wb,#lit5,Wnd`	Wnd = Left Shift Wb by lit5	1	1	N,Z
73	`SUB`	`SUB Acc`(1)	Subtract Accumulators	1	1	OA,OB,OAB, SA,SB,SAB
		`SUB f`	f = f – WREG	1	1	C,DC,N,OV,Z
		`SUB f,WREG`	WREG = f – WREG	1	1	C,DC,N,OV,Z
		`SUB #lit10,Wn`	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		`SUB Wb,Ws,Wd`	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		`SUB Wb,#lit5,Wd`	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
74	`SUBB`	`SUBB f`	f = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		`SUBB f,WREG`	WREG = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		`SUBB #lit10,Wn`	Wn = Wn – lit10 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		`SUBB Wb,Ws,Wd`	Wd = Wb – Ws – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		`SUBB Wb,#lit5,Wd`	Wd = Wb – lit5 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
75	`SUBR`	`SUBR f`	f = WREG – f	1	1	C,DC,N,OV,Z
		`SUBR f,WREG`	WREG = WREG – f	1	1	C,DC,N,OV,Z
		`SUBR Wb,Ws,Wd`	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		`SUBR Wb,#lit5,Wd`	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
76	`SUBBR`	`SUBBR f`	f = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		`SUBBR f,WREG`	WREG = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		`SUBBR Wb,Ws,Wd`	Wd = Ws – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		`SUBBR Wb,#lit5,Wd`	Wd = lit5 – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
77	`SWAP`	`SWAP.b Wn`	Wn = nibble swap Wn	1	1	None
		`SWAP Wn`	Wn = byte swap Wn	1	1	None
78	`TBLRDH`	`TBLRDH Ws,Wd`	Read Prog<23:16> to Wd<7:0>	1	5	None
79	`TBLRDL`	`TBLRDL Ws,Wd`	Read Prog<15:0> to Wd	1	5	None
80	`TBLWTH`	`TBLWTH Ws,Wd`	Write Ws<7:0> to Prog<23:16>	1	2	None
81	`TBLWTL`	`TBLWTL Ws,Wd`	Write Ws to Prog<15:0>	1	2	None
82	`ULNK`	`ULNK`	Unlink Frame Pointer	1	1	SFA
83	`XOR`	`XOR f`	f = f .XOR. WREG	1	1	N,Z
		`XOR f,WREG`	WREG = f .XOR. WREG	1	1	N,Z
		`XOR #lit10,Wn`	Wd = lit10 .XOR. Wd	1	1	N,Z
		`XOR Wb,Ws,Wd`	Wd = Wb .XOR. Ws	1	1	N,Z
		`XOR Wb,#lit5,Wd`	Wd = Wb .XOR. lit5	1	1	N,Z
84	`ZE`	`ZE Ws,Wnd`	Wnd = Zero-extend Ws	1	1	C,Z,N

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 “Electrical Characteristics”** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 “Electrical Characteristics”** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(2)	-40°C to +150°C
Storage temperature	-65°C to +160°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS(3)	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V(3)	-0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(3)	-0.3V to 5.5V
Maximum current out of VSS pin	60 mA
Maximum current into VDD pin(4)	60 mA
Maximum junction temperature	+155°C
Maximum current sourced/sunk by any 4x I/O pin	10 mA
Maximum current sourced/sunk by any 8x I/O pin	15 mA
Maximum current sunk by all ports combined	70 mA
Maximum current sourced by all ports combined(4)	70 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

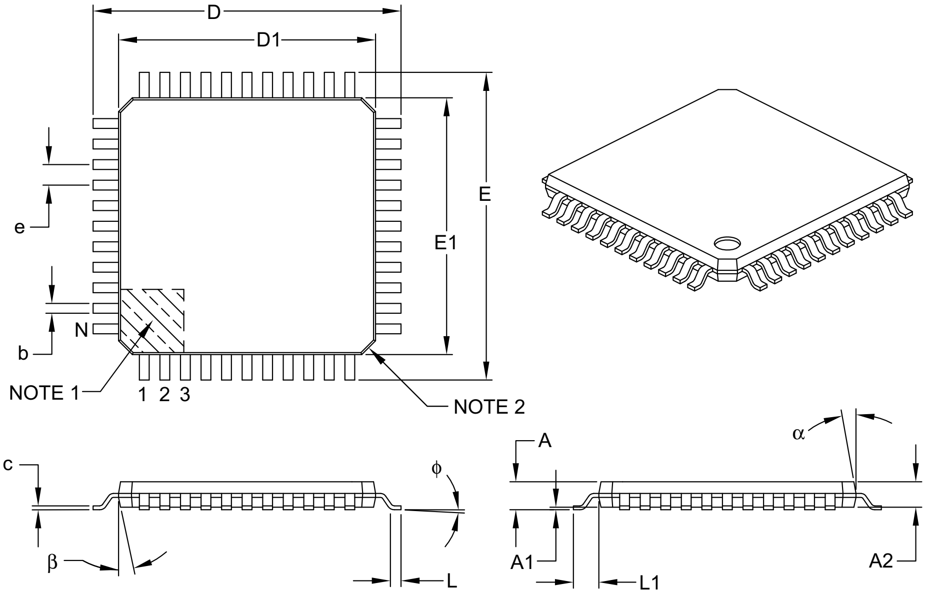
2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Refer to the **“Pin Diagrams”** section for 5V tolerant pins.

4: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

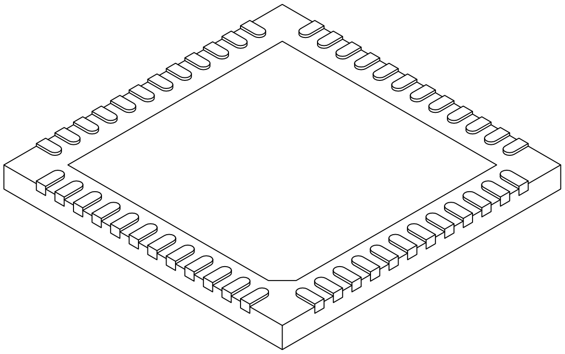
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		48	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.45	4.60	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.45	4.60	4.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

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